separated by a height not less than 1/10 of the dimensions of a plurality of motifs forming said high level, said high surface level representing 1 to 65% of a surface of the substrate.

2. (Amended) The substrate according to claim 1, wherein said substrate is hydrophobic/oleophobic and further comprises an agent chosen from the group consisting of:

a) silicones, and

b) compounds corresponding to the formulas:

$$F_3C(CF_2)_m(CH_2)_nSiX_{3-p} \quad (I)$$
$$\qquad\qquad\qquad\qquad\qquad\qquad\quad |$$
$$\qquad\qquad\qquad\qquad\qquad\qquad\quad R_p$$

and

$$R_{p'}SiX_{4-p'} \quad (II)$$

A2

where m = 0 to 15;

n = 1 to 5;

p = 0, 1 or 2;

R is a linear or branched alkyl group or a hydrogen atom;

X is a hydrolyzable group such as a halogeno, alkoxy, acetoxy, acyloxy, amino, or a NCO group; and

p' = 0, 1, 2 or 3.

3. (Amended) The substrate according to claim 1, wherein said substrate is hydrophilic/oleophilic.

4. (Amended) The substrate according to claim 1, wherein said height ranges between 0.01 and 10 micrometers.

5. (Amended) The substrate according to claim 1, wherein a geometry of said relief does not display periodicity.

6. (Amended) The substrate according to claim 1, wherein a geometry of said relief displays a periodicity.

7. (Amended) The substrate according to claim 1, wherein said low surface level and said high surface level are connected to one another by means of at least one partition approximately perpendicular to a plane of the substrate.

8. (Amended) The substrate according to claim 1, wherein said high surface level displays a continuity in at least one direction of a plane of the substrate.

9. (Amended) The substrate according to claim 8, wherein said relief comprises a multiplicity of approximately identical parallelepipedal objects, said parallelepipedal objects parallel and uniformly spaced.

A2 cont

10. (Amended) The substrate according to claim 1, wherein said high surface level does not display continuity in any direction of a plane of the substrate.

11. (Amended) The substrate according to claim 1, wherein said relief comprises a multiplicity of approximately identical cylindrical craters uniformly distributed on the substrate, a multiplicity of axes of said craters approximately perpendicular to a plane of the substrate.

12. (Amended) The substrate according to claim 1, wherein said relief comprises a discrete series of identical or different objects.

13. (Amended) The substrate according to claim 12, wherein said discrete series of identical or different objects consists of a plurality of cylinders with axes approximately perpendicular to a plane of the substrate.

14. (Amended) The substrate according to claim 13, wherein said relief comprises a multiplicity of approximately identical cylinders of revolution uniformly distributed on the substrate.

15. (Amended) The substrate according to claim 1, wherein said relief is based on at least one compound of at least one of the elements selected from the group consisting of Si, W, Sb, Ti, Zr, Ta, V, Pb, Mg, Al, Mn, Co, Ni, Sn, Zn, In, a plastic and a plastic containing a filler, said compound optionally hardened by means of application of an energy source, or a thermoplastic, and wherein at least one underlying portion of the substrate is composed of a glass, a plastic or combination thereof.

16. (Amended) A substrate according to claim 1, wherein said substrate is a conductor of electricity.

17. (Amended) The substrate according to claim 1, wherein said substrate has anti-reflecting properties.

A2 CONT

18. (Amended) The substrate according to claim 1, wherein said substrate has anti-staining properties.

19. (Amended) A process for formation of a substrate comprising a relief according to claim 1, said process comprising

- applying to a support surface a precursor of liquid to viscous consistency,
- molding a sol-gel from the precursor, then
- consolidating the precursor through evaporation of a solvent.

20. (Amended) A process for formation of a substrate comprising a relief according to claim 1, said process comprising

- applying to a support surface a polymerizable and/or cross-linkable plastic,
- performing polymerization, cross-linking or a combination thereof of said plastic, and
- separating a residual component.

21. (Amended) A process for formation of a substrate comprising a relief according to claim 1, said process comprising

- forming a mask on a surface

- attacking a portion of said surface not protected by the mask, then

- optionally removing the mask.

22. (Amended) A process for formation of a substrate comprising a relief according to claim 1, said process comprising causing a film forming said relief to adhere to a support surface.

23. (Amended) The process according to claim 19, wherein a mold is formed, said mold capable of forming the substrate.

24. (Amended) The process according to claim 19, wherein the substrate is formed

A2 AMEND

25. (Amended) The process according to claim 19, wherein a hydrophobic/oleophobic or hydrophilic/oleophilic agent is incorporated into said substrate comprising a relief.

26. (Amended) The process according to claim 19, further comprising forming a hydrophobic/oleophobic or hydrophilic/oleophilic coating on said relief.

27. (Amended) A glazing comprising a substrate according to claim 1.

Please add the following new claims:

A3

32. (New) The process according to claim 20, wherein a mold is formed, said mold capable of forming said substrate.

33. (New) The process according to claim 21, wherein a mold is formed, said mold capable of forming said substrate.

34. (New) The process according to claim 22, wherein a mold is formed, said mold capable of forming said substrate.

35. (New) The process according to claim 20, wherein the substrate is formed.

36. (New) The process according to claim 21, wherein the substrate is formed.

37. (New) The process according to claim 22, wherein the substrate is formed.

38. (New) The process according to claim 20, wherein a hydrophobic/oleophobic or hydrophilic/oleophilic agent is incorporated into said substrate comprising a relief.

39. (New) The process according to claim 21, wherein a hydrophobic/oleophobic or hydrophilic/oleophilic agent is incorporated into said substrate comprising a relief.

40. (New) The process according to claim 22, wherein a hydrophobic/oleophobic or hydrophilic/oleophilic agent is incorporated into said substrate comprising a relief.

A3 cont

41. (New) The process according to claim 23, wherein a hydrophobic/oleophobic or hydrophilic/oleophilic agent is incorporated into said substrate comprising a relief.

42. (New) The process according to claim 32, wherein a hydrophobic/oleophobic or hydrophilic/oleophilic agent is incorporated into said substrate comprising a relief.

43. (New) The process according to claim 33, wherein a hydrophobic/oleophobic or hydrophilic/oleophilic agent is incorporated into said substrate comprising a relief.

44. (New) The process according to claim 34, wherein a hydrophobic/oleophobic or hydrophilic/oleophilic agent is incorporated into said substrate comprising a relief.

45. (New) The process according to claim 20, further comprising forming a hydrophobic/oleophobic or hydrophilic/oleophilic coating on said relief.

46. (New) The process according to claim 21, further comprising forming a hydrophobic/oleophobic or hydrophilic/oleophilic coating on said relief.

47. (New) The process according to claim 22, further comprising forming a hydrophobic/oleophobic or hydrophilic/oleophilic coating on said relief.

48. (New) The process according to claim 23, further comprising forming a hydrophobic/oleophobic or hydrophilic/oleophilic coating on said relief.

49. (New) The process according to claim 32, further comprising forming a hydrophobic/oleophobic or hydrophilic/oleophilic coating on said relief.

50. (New) The process according to claim 33, further comprising forming a hydrophobic/oleophobic or hydrophilic/oleophilic coating on said relief.

51. (New) The process according to claim 34, further comprising forming a hydrophobic/oleophobic or hydrophilic/oleophilic coating on said relief.

52. (New) The process as claimed in claim 19, wherein the precursor is consolidated with an energy source.

3 A cont

53. (New) The process as claimed in claim 20, wherein the plastic contains a filler.

54. (New) The process as claimed in claim 53, wherein the filler is a mineral filler.

55. (New) The process as claimed in claim 20, wherein said residual component is a solvent.

56. (New) The process as claimed in claim 20, wherein the precursor is consolidated with an energy source.

57. (New) The process as claimed in claim 21, wherein the mask is formed by a technique selected from the group consisting of serigraphy, ink-jet printing, lithography, and engraving.

58. (New) The process as claimed in claim 57, wherein the lithography is photolithography.

59. (New) The process as claimed in claim 58, wherein the engraving is ionic reactive engraving.

60. (New) The process as claimed in claim 21, wherein the surface is attacked by chemical means.

EP A3